

Title (en)
LAPPING AND POLISHING DEVICE

Title (de)
POLIER- ODER SCHLEIFVORRICHTUNG

Title (fr)
DISPOSITIF DE RODAGE OU POLISSAGE

Publication
EP 1131186 B1 20021030 (FR)

Application
EP 99956065 A 19991117

Priority
• FR 9902817 W 19991117
• FR 9814563 A 19981119

Abstract (en)
[origin: FR2786118A1] Polishing surface has recessed parts (1) forming reservoirs for the abrasive suspension independent of each other. The recessed parts (1) are defined by partitions (2), the top walls of which in co-operation with the abrasive suspension forming active zones for lapping and polishing. The partitions (2) have an essentially constant height over the whole surface of the device prior to it being used. A polishing or lapping device has a surface on which the components to be polished are placed with an interposed abrasive suspension and at a given pressure.

IPC 1-7
B24B 37/04

IPC 8 full level
B24B 37/16 (2012.01); **B24D 13/14** (2006.01)

CPC (source: EP US)
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US 6837780 B1 20050104; AT E226868 T1 20021115; DE 69903748 D1 20021205; DE 69903748 T2 20030724; DK 1131186 T3 20030120; EP 1131186 A1 20010912; EP 1131186 B1 20021030; FR 2786118 A1 20000526; FR 2786118 B1 20001222; WO 0030806 A1 20000602

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